



73rd Pre. Amata  
M. Brunson  
8/8/02

501.35250CX3

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: TANAKA et al

Serial No.: 09/904,839

Filed: July 16, 2001

For: Lead Frame And Semiconductor Device Using The  
Lead Frame And Method Of Manufacturing The Same

Group: 2814

Examiner:

**PRELIMINARY AMENDMENT**

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

July 24, 2002

Sir:

Prior to examination on the merits of this application, please amend the  
above-identified application as follows:

**IN THE CLAIMS:**

Please add the following new claims to the application.

--7. A semiconductor device comprising:

a substrate;

a semiconductor chip mounted on one surface of said substrate, said  
semiconductor chip having an integrated circuit and bonding pads formed on a main  
surface thereof, said main surface of said semiconductor chip having a quadrilateral  
shape, said bonding pads being disposed along four sides of said main surface of  
said semiconductor chip;

a plurality of conductors being disposed on said one surface of said substrate  
to surround said semiconductor chip along the four sides thereof;